

## AMENDMENTS TO THE CLAIMS

Claims 1-25 (Cancelled).

26. (Currently Amended) A plating apparatus comprising:

an ozone water process chamber configured to bring a surface of a substrate into contact with ozone water so as to create a reformed surface of an organic resist film on the substrate, and so as to remove organic substances remaining on exposed surfaces of an underlying film at a bottom of a resist pattern of the organic resist film;

a plating chamber configured to plate the exposed surfaces of the underlying film at the bottom of the resist pattern surface of the substrate brought into contact with the ozone water; and

a frame housing at least said ozone water process chamber and said plating chamber.

27. (Original) The plating apparatus as recited in claim 26, further comprising an acid treatment chamber configured to bring the surface of the substrate, brought into contact with the ozone water, into contact with an acid liquid, said acid treatment chamber being housed by said frame.

28. (Original) The plating apparatus as recited in claim 26, further comprising an ozone water generator configured to dissolve an ozone gas in pure water by diffusion and dissolution through an ozone dissolution membrane to generate the ozone water.

Claims 29-43 (Cancelled).

44. (New) The plating apparatus as recited in claim 28, wherein said ozone water generator includes an ozonizer for producing ozone gas from oxygen, said ozone dissolution

membrane being arranged to receive the ozone gas from said ozonizer and ultrapure water, and to dissolve the ozone gas into the ultrapure water by diffusion and dissolution.

45. (New) The plating apparatus as recited in claim 26, wherein said ozone water process chamber includes a rotatable stage for supporting the substrate in a horizontal orientation, and a spray nozzle having a plurality of spray heads for spraying the ozone water onto the surface of the substrate while the substrate is being rotated by said rotatable stage.

46. (New) The plating apparatus as recited in claim 45, wherein said ozone water process chamber further includes a vertically adjustable sidewall surrounding said rotatable stage, and a slider for moving said sidewall in a vertical direction.

47. (New) The plating apparatus as recited in claim 26, wherein said ozone water process chamber includes a tank, substrate holder for holding the substrate in a vertical orientation within said tank, and a supply pipe having a plurality of ejection nozzles for spraying the ozone water onto the surface of the substrate while the substrate is being held by said substrate holder in the vertical orientation within said tank.